# XBF10A40S-G



1.0A Fast Recovery Rectifier

#### **■**FEATURES

 $\begin{array}{lll} \textbf{Forward Current} & : I_{F(AV)} = 1.0A \\ \textbf{Reverse Recovery Time} & : trr = 35 ns \ (TYP.) \\ \textbf{Environmentally Friendly} & : EU \ RoHS \ Compliant \\ \end{array}$ 

# **■**APPLICATIONS

- ●LED lighting
- Power supply module
- AC adapter, Battery charger

#### ■MARKING



①23456 : Control Number ⑦89 : Marking Code



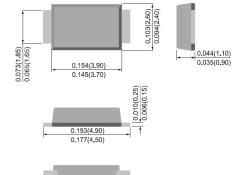
Ta=25°C

PARAMETER	SYMBOL	RATINGS	UNITS
Repetitive Peak Reverse Voltage	$V_{RM}$	400	V
RMS Voltage	$V_{RMS}$	280	V
Reverse Voltage (DC)	$V_R$	400	V
Forward Current (Average)	I <sub>F(AV)</sub>	1	Α
Non Continuous Forward Surge Current (*1)	I <sub>FSM</sub>	30	А
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 <b>~</b> +150	°C

■ ABSOLUTE MAXIMUM RATINGS

# ■ PACKAGING INFORMATION

●SMAF Unit: inch (mm)





# **■**ELECTRICAL CHARACTERISTICS

Ta=25°C

PARAMETER SYMBOL	CVMDOL	TEST CONDITIONS	LIMITS			LINUTO
	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =1A, Pulse measurement	-	-	1.25	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =V <sub>RM</sub>	-	-	1	μΑ
Terminal Capacitance	Ct	V <sub>R</sub> =4V, f=1MHz	-	15	-	pF
Reverse Recovery Time	trr	I <sub>F</sub> =0.5A, I <sub>R</sub> =1A, irr=0.25A	-	ı	35	ns

<sup>(\*1) 60</sup>Hz single half sine wave

# **■**PRODUCT NAME

PRODUCT NAME	PACKAGE	ORDER UNIT	MARKING CODE
XBF10A40S-G * SMAF		3,000pcs / Reel	1GF

<sup>\*</sup> The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant.

# **■**NOTES ON USE

1. Please use this IC within the absolute maximum ratings.

Even within the ratings, in case of high load use continuously such as high temperature, high voltage, high current and thermal stress may cause reliability degradation of the IC.

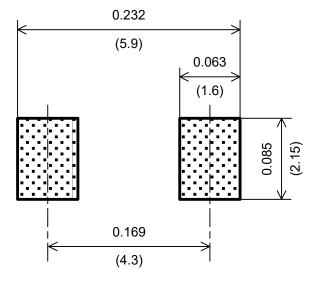
2. Torex places an importance on improving our products and their reliability.

We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

# ■REFERENCE PATTERN LAYOUT

**●**SMAF

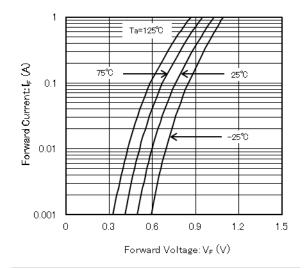
Unit: inch (mm)



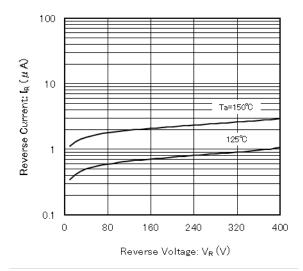
<sup>\*</sup> However, the product uses high-melting-point solder paste and lead glass, both of which are not compliant with EU RoHS.

# **■**TYPICAL PERFORMANCE CHARACTERISTICS

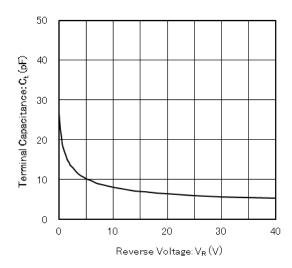
#### (1) Forward Current vs. Forward Voltage



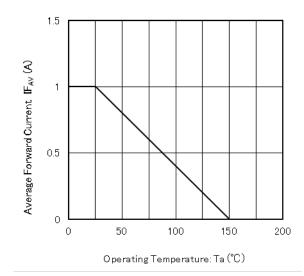
#### (2) Reverse Current vs. Reverse Voltage



#### (3) Terminal Capacitance vs. Reverse Voltage



#### (4) Average Forward Current vs. Operating Temperature

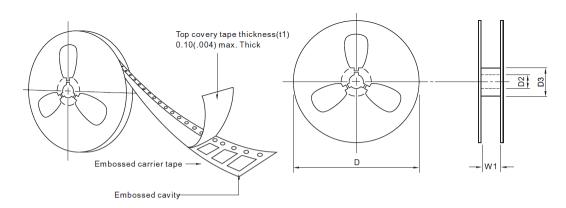


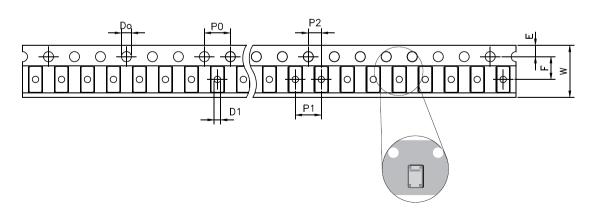
# XBE10A40SEG

# **■**TAPING SPECIFICATIONS

#### ● SMAF

Unit: mm





SYMBOL	mm
D <sub>0</sub>	1.55 ± 0.05
D1	1.00 ± 0.05
E	1.75 ± 0.10
F	5.50 ± 0.10
P <sub>0</sub>	4.00 ± 0.10
P1	4.00 ± 0.10
P2	2.00 ± 0.05
W	12.0 ± 0.3
D2	13.5 ± 0.5
D3	min. 57.0
W1	min. 13.7 , max. 16.7
D	178.0 ± 2.0

- 1. The product and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date.
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- 4. The product is neither intended nor warranted for use in equipment of systems which require extremely high levels of quality and/or reliability and/or a malfunction or failure which may cause loss of human life, bodily injury, serious property damage including but not limited to devices or equipment used in 1) nuclear facilities, 2) aerospace industry, 3) medical facilities, 4) automobile industry and other transportation industry and 5) safety devices and safety equipment to control combustions and explosions. Do not use the product for the above use unless agreed by us in writing in advance.
- 5. Although we make continuous efforts to improve the quality and reliability of our products; nevertheless Semiconductors are likely to fail with a certain probability. So in order to prevent personal injury and/or property damage resulting from such failure, customers are required to incorporate adequate safety measures in their designs, such as system fail safes, redundancy and fire prevention features.
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- 7. Please use the product listed in this datasheet within the specified ranges.
- 8. We assume no responsibility for damage or loss due to abnormal use.
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